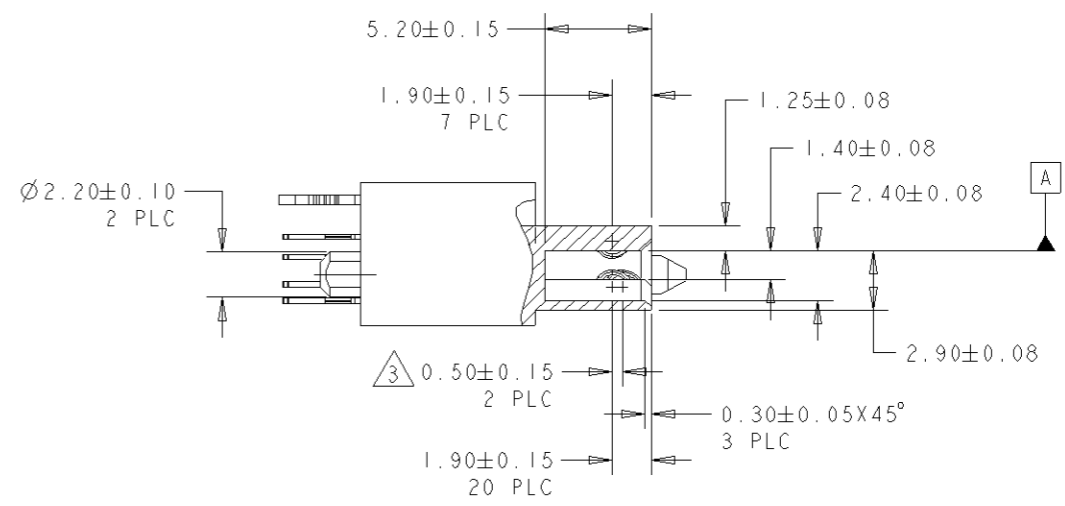
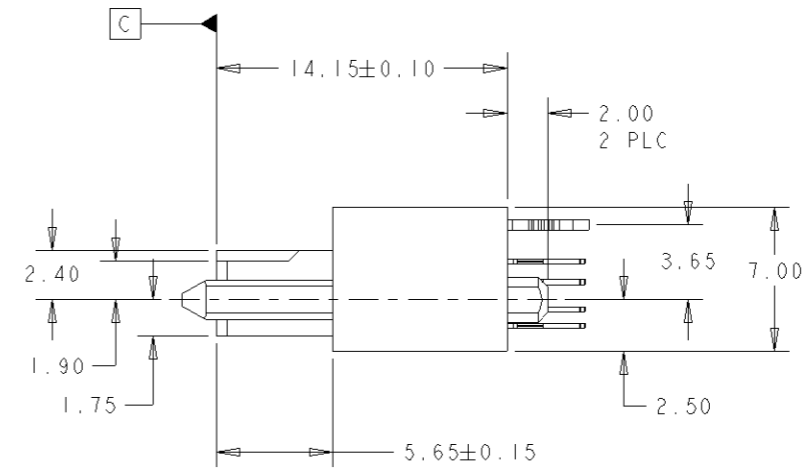
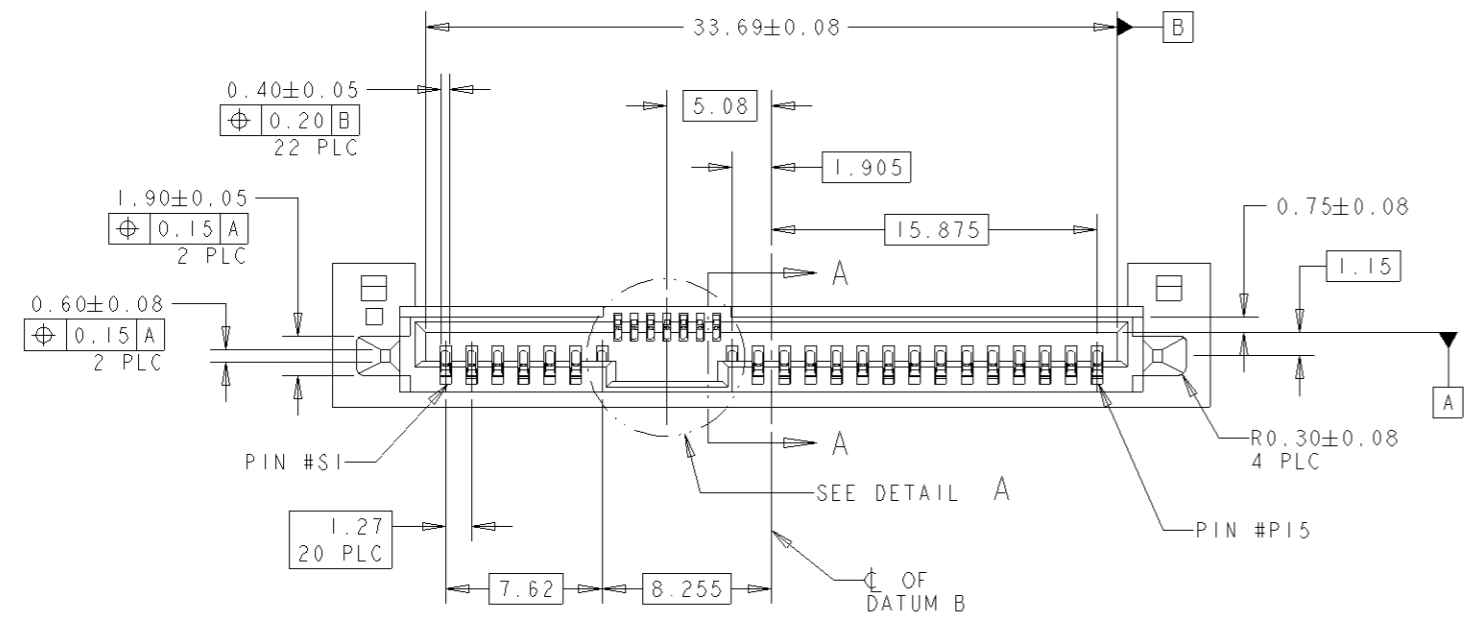
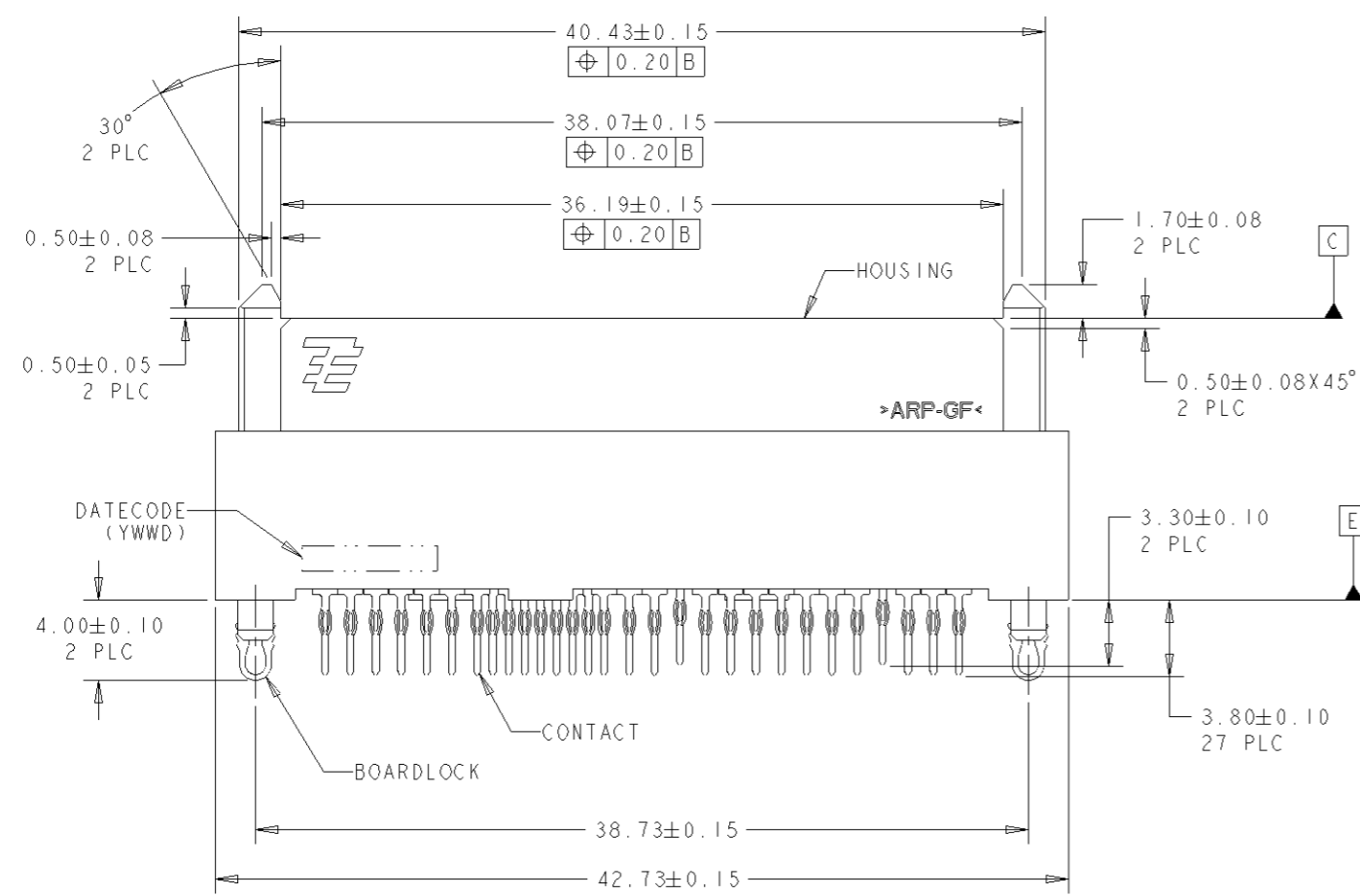


LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD		
	A	NPR PER ECR-09-000416	12JAN09	LSK	LSF		



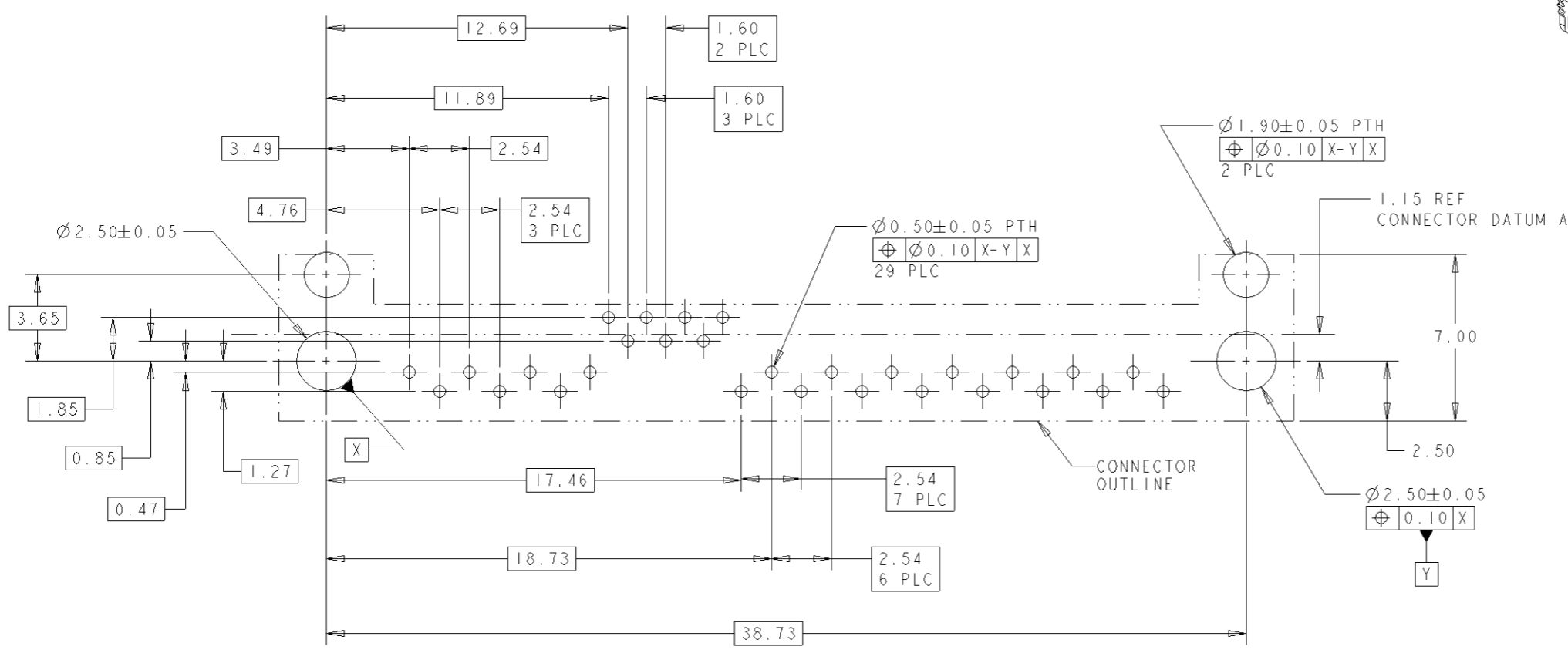
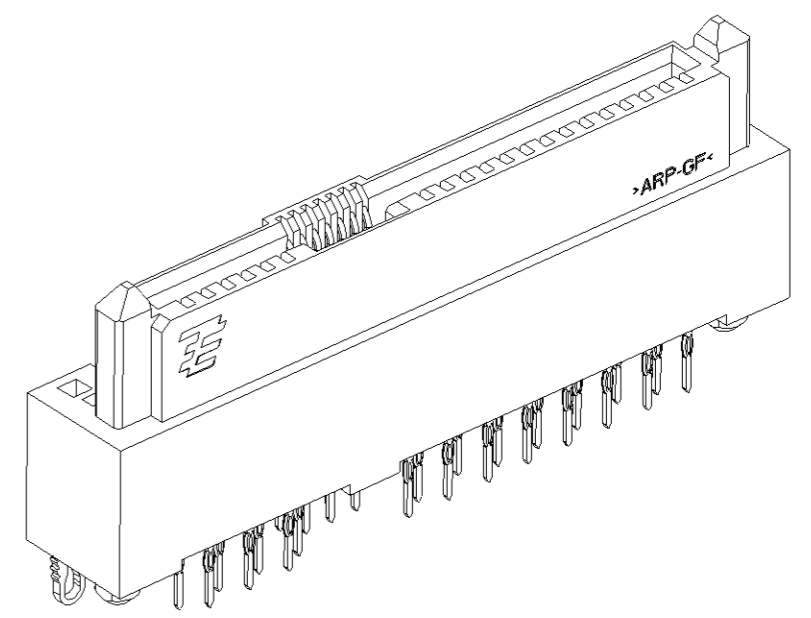
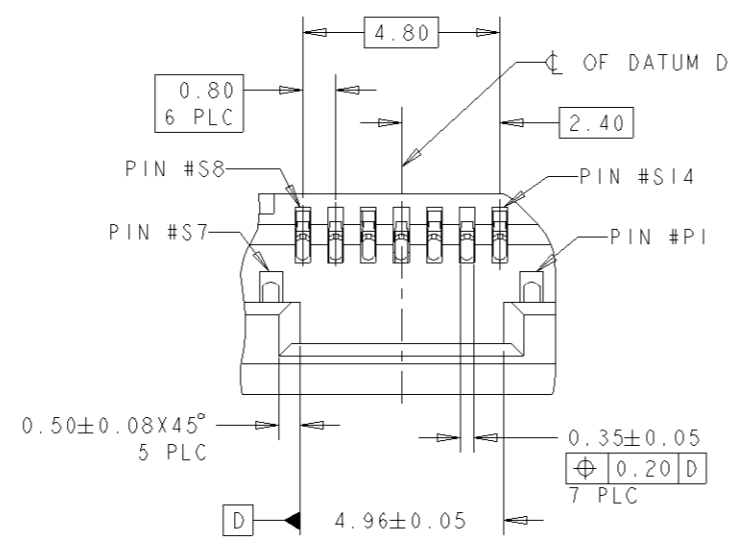
- NOTES:
- 1 MATERIAL:
HOUSING: HIGH TEMP THERMOPLASTIC, UL94V-0, COLOR: BLACK
CONTACT: COPPER ALLOY
BOARDLOCK: COPPER ALLOY
 - 2 FINISH:
CONTACT MATING AREA: MIN 0.20um GOLD PLATING
CONTACT SOLDER TAIL: MIN 2.54um MATTE TIN PLATING
BOARDLOCK: MIN 2.54um MATTE TIN PLATING
UNDERPLATE: MIN 1.27um NICKEL PLATING
 - 3 PIN #P4 AND #P12 ONLY



1735690-1
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.		DWN SK LEAW 04JUL2008	Tyco Electronics Corporation Singapore	
DIMENSIONS: mm		CHK SF LEONG 12JAN2009	NAME SAS BACKPLANE RECEPTACLE, VERTICAL, EXTENDED HEIGHT, PRESS-FIT	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.20 3 PLC ± 4 PLC ± ANGLES ±3° FINISH		APVD SF LEONG 12JAN2009	DRAWING NO 108-51067	
MATERIAL		APPLICATION SPEC	SIZE A2	CAGE CODE 00779
1		WEIGHT	DRAWING NO C=1735690	
2		CUSTOMER DRAWING	SCALE 4:1	SHEET 1 OF 2

LOC	DIST	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
DY	-	-	-	SEE SHEET 1	-	-	-



RECOMMENDED PCB LAYOUT
 PCB THICKNESS: 2.40mm MIN
 SCALE 6:1

THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.		DWN SK LEAW 04 JUL 2008	Tyco Electronics Tyco Electronics Corporation Singapore	
DIMENSIONS: mm		CHK SF LEONG 12 JAN 2009	NAME SAS BACKPLANE RECEPTACLE, VERTICAL, EXTENDED HEIGHT, PRESS-FIT	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.20 3 PLC ± 4 PLC ± ANGLES ±3° FINISH -		APVD SF LEONG 12 JAN 2009	DRAWING NO C=1735690	
MATERIAL -		PRODUCT SPEC 108-51067	SIZE A2	CAGE CODE 00779
		APPLICATION SPEC -	SCALE 4:1	
		WEIGHT -	SHEET 2 OF 2	
		CUSTOMER DRAWING	REV A	